

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
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NO SUN PARK	07/27/2015
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PROPERTY NUMBERS Total: 2	
Property Type	Number
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Application Number:	16740755
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DATE SIGNED:	11/06/2023
Total Attachments: 3	
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ASSIGNMENT

File No.: 28435US02 Serial No.: 14/815,435
Inventors: Jong Sik Paek Filing Date: July 31, 2015
 No Sun Park

For good and valuable consideration, the receipt and sufficiency whereof are hereby acknowledged, each of the undersigned hereby assigns to Amkor Technology, Inc., incorporated under the laws of the state of Delaware, its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, entitled "A SEMICONDUCTOR PACKAGE AND MANUFACTURING METHOD THEREOF" and identified as File No. 28435US02, in the offices of MEANDREWS, HELD & MALLOY, LTD., and in said application and any and all other applications, both United States and foreign, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States and foreign countries, which may be obtained on any of said applications, and in any continuation, continuation-in-part, divisional, re-examination, reissue or extension of such patents, and further assigns to said assignee the priority right provided by the International Convention.

Each of the undersigned hereby authorizes and requests the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee.

Each of the undersigned hereby authorizes and requests the attorneys of record in said application to insert in this assignment the filing date and serial number of said application when officially known.

Each of the undersigned warrants himself/herself to be the owner of the entire right, title and interest in said invention or improvements and to have the right to make this assignment, and further warrants that there are no outstanding prior assignments, licenses, or other encumbrances on the interest herein assigned.

For said considerations, each of the undersigned hereby agrees, upon the request and at the expense of said assignee, its successors and assigns, to execute any and all continuation, continuation-in-part, divisional, re-examination, extension, and substitute applications for said invention or improvements, and any necessary oath, affidavit or declaration relating thereto, and any application for the reissue, re-examination, or extension of any Letters Patent that may be granted upon said application, and any and all applications and other document for Letters Patent in foreign countries on said invention or improvements, that said assignee, its successors or assigns may deem necessary or expedient, and for the said considerations each of the undersigned authorizes said assignee to apply for patents for said invention or improvements in its own name in such countries where such procedure is proper and further agrees, upon the request of said assignee, its successors and assigns, to cooperate to the best of the ability of the undersigned with said assignee, its successors and assigns, in any proceedings or transactions involving such applications or patents, including the preparation and execution of preliminary statements, giving and producing evidence and performing any and all other acts necessary to

obtain or enforce said Letters Patent, both United States and foreign, and vest all rights therein hereby conveyed in the assignee, its successors and assigns, whereby said Letters Patent will be held and enjoyed by the said assignee, its successors and assigns, to the full end of the term for which said Letters Patent will be granted, as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment had not been made. This obligation to cooperate exists both during and after the undersigned's employment.

In the event the assignee is unable to secure the undersigned's signature on any document required by the assignee under this agreement or any document necessary to apply for, establish, prosecute, obtain, or enforce any patent, copyright, or other right or protection relating to said inventions or improvements, whether due to mental or physical incapacity or other cause, the undersigned hereby irrevocably designates and appoints the assignee and each of its duly authorized officers and agents as his or her agent and attorney-in-fact, to act for and in his or her behalf and stead to execute and file any documents and to do all other lawfully permitted acts to further prosecution, issuance, and enforcement of patents, copyrights, or other rights or protections relating to said inventions or improvements with the same force and effect as if executed and delivered by the undersigned.

Executed this 21 day of July, 2015.

Jong Se Park
Jong Se Park

Witnessed By:

[Signature]
Signature

July 21, 2015
Date

Dohyun Na
Printed Name

Executed this 27 day of July, 2015.

Na Sun Park
Signature

Witnessed By:

[Signature]
Signature

July 27, 2015
Date

Do Hyun Na
Printed Name